

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	20	257/E23.107	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/30 18:37
L2	61	257/E23.124	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/30 18:37
L3	3801	257/706	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/30 18:37
L4	2829	257/707	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/30 18:55
L5	3637	257/712	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/30 19:20
L6	4491	257/787	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/12/30 19:45
S1	10	"20010023986" or "6,313,015"-pn. or "6,407,922"-pn. or "20020130311" or "20020175408" or "20030039602" or "20030151030"	US_PGPUB; USPAT	OR	OFF	2008/07/04 22:50
S2	1	"20070040266"	US_PGPUB; USPAT	OR	OFF	2008/07/04 23:09

S3	16	257/E23.107	US_PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 23:10
S4	44	257/E23.124	US_PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 23:10
S5	3645	257/706	US_PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 23:12
S6	2697	257/707	US_PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 23:13
S7	96	(semiconductor or die or dice or chip or IC) and (mold\$3 or encapsulat\$3 or cover \$3 near resin) with (nanoelements or nanotubes or nano near (elements or particles or tubes))	USPAT	OR	OFF	2008/07/04 23:37
S8	155	(semiconductor or die or dice or chip or IC) and (mold\$3 or encapsulat\$3 or cover \$3 near resin) with (nanoelements or nanotubes or nano near (elements or particles or tubes))	USPAT	OR	ON	2008/07/04 23:37
S9	3484	257/712	US_PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/07/04 23:38
S10	578	257/741	USPAT	OR	OFF	2008/07/05 18:16
S11	379942	(chip or IC)	USPAT	OR	OFF	2008/07/05 18:19

S12	563686	(chip or IC or die)	USPAT	OR	OFF	2008/07/05 18:20
S13	566737	( die or dice or chip or IC)	USPAT	OR	OFF	2008/07/05 18:20
S14	425701	(semiconductor)	USPAT	OR	OFF	2008/07/05 18:25
S15	634694	( die or dice or chip or IC)	USPAT	OR	ON	2008/07/05 18:25
S16	647101	(mold\$3 or encapsula \$4)	USPAT	OR	OFF	2008/07/05 18:27
S17	8362	(cover\$3 near resin)	USPAT	OR	OFF	2008/07/05 18:27
S18	26720	(nanoelements or nanotubes oe nanowires)	USPAT	OR	OFF	2008/07/05 18:27
S19	956201	(nanoelements or nanotubes oe nanowires)	USPAT	OR	ON	2008/07/05 18:28
S20	194460	S15 and S19	USPAT	OR	ON	2008/07/05 18:30
S21	48956	S20 and S16	USPAT	OR	ON	2008/07/05 18:31
S22	7421	S16 with S19	USPAT	OR	ON	2008/07/05 18:32
S23	2199	S22 and S15	USPAT	OR	ON	2008/07/05 18:33
S24	871408	S14 or S15	USPAT	OR	OFF	2008/07/05 18:35
S25	2497	S24 and S22	USPAT	OR	ON	2008/07/05 18:36
S26	4348	257/787	US_PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/05 20:18
S27	2	"6407922".pn.	US_PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/05 20:20
S28	3	"6838776".pn.	US_PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/05 20:26

S29	688	257/789	US_PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/05 20:41
S30	2	"6998434".pn.	US_PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/05 20:42
S31	442	257/795	US_PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/05 21:06
S32	72	977/843	US_PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/05 21:34
S33	272	977/742	US_PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/05 21:35
S34	31	977/724	US_PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/07/05 21:35

12/30/08 8:11:25 PM

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